



## Call For Papers

### WCSP 2024: Semantic Communication and Networked Intelligence Symposium

October 24-26, 2024, Hefei, China

<http://www.ic-wcsp.org>

**Overview:** The International Conference on Wireless Communications and Signal Processing (IC-WCSP) aims to gather international researchers from academia and industry to meet and exchange ideas and recent research works across the broad field of ICT technologies. The event of WCSP 2024 will be held in Hefei, Anhui, China, on October 24-26, 2024, with the theme “Charging up wireless communications and signal processing with intelligence”. The conference will be sponsored and organized by University of Science and Technology of China, China, and technically co-sponsored by IEEE and IEEE Communications Society.

**Scope:** Semantic Communication and Networked Intelligence Symposium seeks original contributions in the following topical areas, plus others that are not explicitly listed but are closely related:

- Semantic and task-oriented communications
- Network architecture for semantic communications and networked intelligence
- Multiple access or radio transmission technologies for semantic communications
- Distributed edge learning for network intelligence: federated learning, split learning, in-device learning, etc
- Emerging coding technologies for information processing and transmission over wireless channels
- AIGC for network resource provisioning and management
- Integration of semantic communication with emerging topics, e.g., age of information, satellite communication, reconfigurable intelligent surface (RIS), etc.
- Generative AI for semantic communications
- Privacy and security issues
- Standards and prototypes for semantic communication and network intelligence

### Important Dates:

Full Paper Submission: June 25, 2024

Acceptance Notification: August 25, 2024

Final Paper Submission: September 5, 2024

**Symposium Co-Chairs:**

Xiaodong Xu,, Beijing University of Posts and Telecommunications, China

Dusit Niyato, Nanyang Technological University, Singapore

Sihai Zhang, University of Science and Technology of China, China

Shuo Shao, Shanghai Jiao Tong University, China

Wei Wang, Zhejiang University, China